

#### DGTD65T40S1PT

#### 650V FIELD STOP IGBT IN TO-247

#### **Description**

The DGTD65T40S1PT is produced using advanced field stop trench IGBT technology, which provides excellent quality and high-switching performance.

#### **Features**

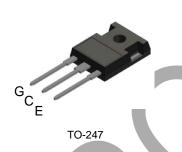
- High Speed Switching & Low Power Loss
- V<sub>CE(sat)</sub> = 1.95V @ I<sub>C</sub> = 40A
- High Input Impedance
- $t_{rr} = 80$ ns (typ) @  $di_F/dt = 1000$ A/ $\mu$ s
- $E_{off} = 0.3 \text{mJ} @ T_{C} = 25 ^{\circ}\text{C}$
- Maximum Junction Temperature 175°C
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

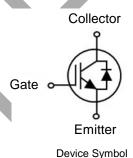
#### **Applications**

- UPS
- Welder
- Solar Inverter
- IH Cooker

#### **Mechanical Data**

- Case: TO-247 (Type MC)
- Case Material: Molded Plastic. "Green" Molding Compound.
- UL Flammability Classification Rating 94V-0
- Terminals: Finish—Matte Tin Plated Leads.
   Solderable per MIL-STD-202, Method 208 @3
- Weight: 5.6 grams (Approximate)





### Ordering Information (Note 4)

Product	Marking	Quantity
DGTD65T40S1PT	DGTD65T40S1	450 per Box in Tubes (Note 5)

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.
- 5. 30 devices per tube.

### **Marking Information**



J;; = Manufacturer's Marking
DGTD65T40S1 = Product Type Marking Code
YY = Year (ex: 18 = 2018)
LLLLL = Lot Code
WW = Week (01 to 53)



# **Absolute Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Collector-Emitter Voltage		$V_{CE}$	650	V	
DC Collector Current limited by T	$T_C = 25^{\circ}C$		80	Α	
DC Collector Current, limited by T <sub>vjmax</sub>	$T_{C} = 100^{\circ}C$	Ic	40	А	
Pulsed Collector Current, tp limited by Tvjmax	I <sub>Cpuls</sub>	160	Α		
Turn Off Safe Operating Area V <sub>CE</sub> ≤ 600V, T <sub>vj</sub> = 175°C		_	160	Α	
Diada Farward Current limited by T	$T_C = 25^{\circ}C$	lF	40	Α	
Diode Forward Current limited by T <sub>vjmax</sub>	$T_{C} = 100^{\circ}C$		20	Α	
Diode Pulsed Current, tp limited by Tvjmax	I <sub>Fpuls</sub>	160	Α		
Gate-Emitter Voltage		$V_{GE}$	±20	V	
Short Circuit Withstand Time $V_{CC} \le 400V$ , $V_{GE} = 15V$ , $T_{Vj} = 150^{\circ}C$ Allowed Number of Short Circuits < 1000		tsc			
			5		
			5	μs	
Time Between Short Circuits ≥ 1.0s					

# Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Power Dissipation Linear Derating Factor (Note 6)	Pn	341	W	
T <sub>C</sub> = 100°C	. 5	170		
Thermal Resistance, Junction to Ambient (Note 6)	$R_{\theta JA}$	40		
Thermal Resistance, Junction to Case for IBGT (Note 6)	R <sub>0</sub> JC	0.44	°C/W	
Thermal Resistance, Junction to Case for Diode (Note 6)	$R_{ heta JC}$	1.20		
Operating Temperature	T <sub>vj</sub>	-40 to +175	°C	
Storage Temperature Range	T <sub>STG</sub>	-55 to +150	C	

6. When mounted on a standard JEDEC 2-layer FR-4 board.

Note:





# Electrical Characteristics (@T<sub>vj</sub> = +25°C, unless otherwise specified.)

Parameter		Symbol	Min	Тур	Max	Unit	Condition	
STATIC CHARACTERISTICS								
Collector-Emitter Breakdown Voltage		BV <sub>CES</sub>	650	_	_	V	$I_C = 2mA$ , $V_{GE} = 0V$	
T.:	= 25°C		_	1.95	2.40			
	= 175°C	$V_{CE(sat)}$	_	2.30	_	V	$I_C = 40A$ , $V_{GE} = 15V$	
Tvi	= 25°C		_	1.30	1.90			
Diode Forward Voltage T <sub>vi</sub>	= 125°C	$V_{F}$	_	1.15	_	V	$V_{GE} = 0V, I_F = 20A$	
	= 175°C	1	_	1.10	_			
Gate-Emitter Threshold Voltage		$V_{GE(th)}$	4.0	5.0	6.0	V	$V_{CE} = V_{GE}, I_{C} = 0.58mA$	
Izero Gate Voltage Collector Current	= 25°C = 175°C	I <sub>CES</sub>	<u> </u>		40 1000	μA	V <sub>CE</sub> = 650V, V <sub>GE</sub> = 0V	
Gate-Emitter Leakage Current		I <sub>GES</sub>	_	_	±100	nA	$V_{GE} = 20V, V_{CE} = 0V$	
Transconductance		<b>G</b> FS	_	17.0	-	S	$V_{CE} = 20V, I_{C} = 40A$	
DYNAMIC CHARACTERISTICS								
Total Gate Charge		$Q_{g}$	_	219			Vor - 520V la - 40A	
Gate-Emitter Charge		Q <sub>ge</sub>	_	26	-	nC	$V_{CE} = 520V, I_{C} = 40A,$ $V_{GE} = 15V$	
Gate-Collector Charge		$Q_{gc}$	_	115			VGE TOV	
Input Capacitance		Cies		2818	_		V <sub>CE</sub> = 25V, V <sub>GE</sub> = 0V, f = 1MHz	
Reverse Transfer Capacitance		Cres	_	131		pF		
Output Capacitance		C <sub>oes</sub>	Ĭ	209	_		1 - 1101112	
Internal Emitter Inductance Measured 5m From Case	m (0.197")	L <sub>E</sub>	_	13		nH	_	
Short Circuit Collector Current Max. 1000 Short Circuits. Time Between Short Circuits ≥ 1.0s		I <sub>C(SC)</sub>	_	180		Α	$V_{GE} = 15V, V_{CC} = 400V,$ $t_{SC} \le 5\mu s, T_{vj} = 150^{\circ}C$	
SWITCHING CHARACTERISTICS							,	
Turn-on Delay Time		t <sub>d(on)</sub>	_	58	_			
Rise time		tr		54	_		$\begin{aligned} &V_{GE}=15\text{V},V_{CC}=400\text{V},\\ &I_{C}=40\text{A},R_{G}=7.9\Omega,\\ &Inductive\;Load,\\ &T_{vj}=25^{\circ}\text{C} \end{aligned}$	
Turn-off Delay Time		t <sub>d(off)</sub>		245	_	ns		
Fall Time		t <sub>f</sub>	<b>—</b>	40				
Turn-on Switching Energy		Eon	T-	1.15	_			
Turn-off Switching Energy		E <sub>off</sub>	-	0.35	ı	mJ		
Total Switching Energy		E <sub>ts</sub>		1.50	_			
Reverse Recovery Time		t <sub>rr</sub>	<b>7</b> -	80	_	ns	1 204	
Reverse Recovery Current		Irr		25	_	$I_F = 20A,$ $d_{iF}/dt = 1000A/\mu s,$		
Reverse Recovery Charge		$Q_{rr}$	_	1.0	_	μC	$T_{vi} = 25^{\circ}C$	
Rate of Fall of Reverse Crecovery Current d	uring t <sub>b</sub>	di <sub>rr</sub> /dt	_	-950	_	A/µs	1 VJ = 23 O	
Turn-on Delay Time		t <sub>d(on)</sub>	_	61	_			
Rise time		t <sub>r</sub>		60		ns	$V_{GE}$ = 15V, $V_{CC}$ = 400V, $I_{C}$ = 40A, $R_{G}$ = 7.9 $\Omega$ , Inductive Load, $T_{vj}$ = 175°C	
Turn-off Delay Time		t <sub>d(off)</sub>		260		113		
Fall Time		t <sub>f</sub>	_	38	_			
Turn-on Switching Energy		E <sub>on</sub>	_	1.80	_			
Turn-off Switching Energy		E <sub>off</sub>	_	0.38	_	mJ   10j = 173 0		
Total Switching Energy	7	E <sub>ts</sub>		2.18				
Reverse Recovery Time		t <sub>rr</sub>	_	145	_	ns	I <sub>F</sub> = 20A,	
Reverse Recovery Current		I <sub>rr</sub>	_	44	_	Α	di <sub>F</sub> /dt = 1000A/μs,	
Reverse Recovery Charge		Q <sub>rr</sub>	_	3.2	_	μC	T <sub>vi</sub> = 175°C	
Rate of Fall of Reverse Crecovery Current d	uring t <sub>b</sub>	di <sub>rr</sub> /dt	_	-680	_	A/µs   10/ = 173 C		



# Typical Performance Characteristics (@TA = +25°C, unless otherwise specified.)

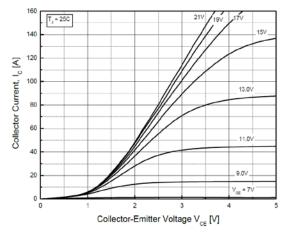


Fig.1 Typical Output Characteristics(T<sub>J</sub>=25°C)

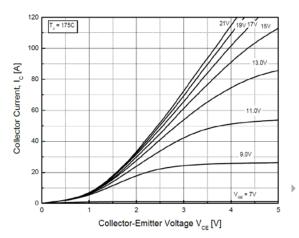


Fig.2 Typical Output Characteristics(T<sub>J</sub>=175°C)

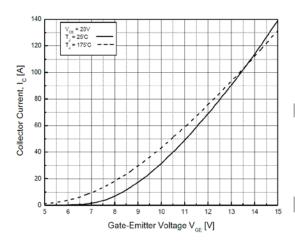


Fig.3 Typical Transfer Characteristics

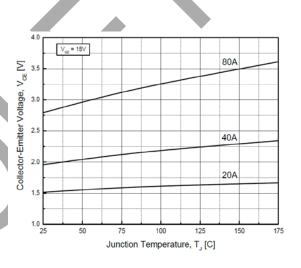


Fig.4 Typical Collector-Emitter Saturation Voltage
-Junction Temperature

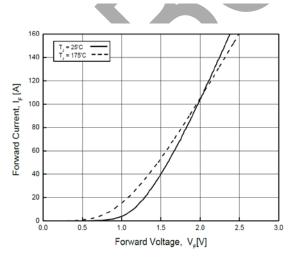


Fig.5 Diode Forward Characteristics

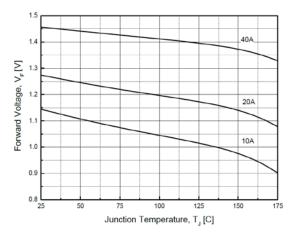


Fig.6 Diode Forward-Junction Temperature



# **Typical Performance Characteristics** (continued)

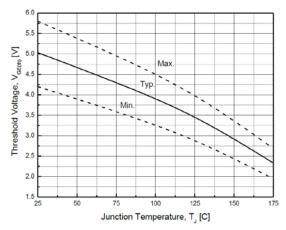


Fig.7 Threshold Voltage-Junction Temperature

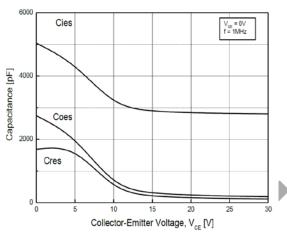


Fig.8 Typical Capacitance

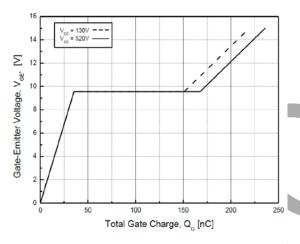


Fig.9 Typical Gate Charge

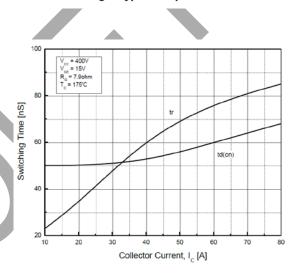


Fig.10 Typical Turn on-Collector Current

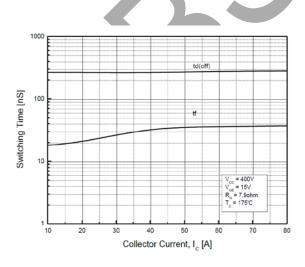


Fig.11 Typical Turn off-Collector Current

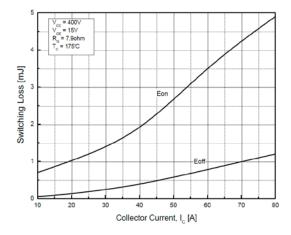


Fig.12 Switching Loss-Collector Current



# **Typical Performance Characteristics** (continued)

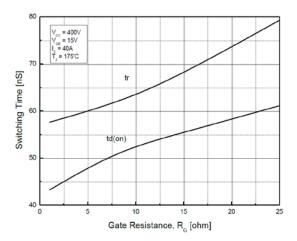


Fig.13 Turn on Characteristics-Gate Resistance

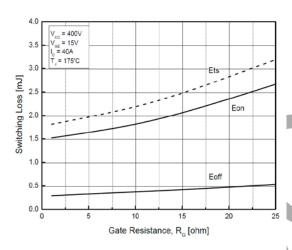


Fig.15 Switching Loss-Gate Resistance

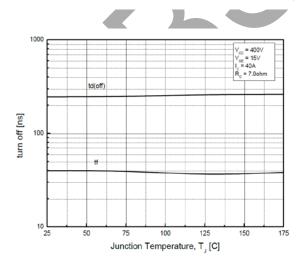


Fig.17 Turn off Characteristics
-Junction Temperature

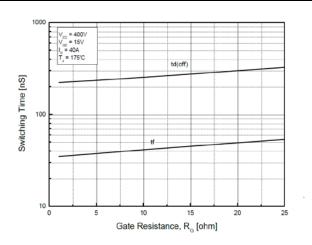


Fig.14 Turn off Characteristics-Gate Resistance

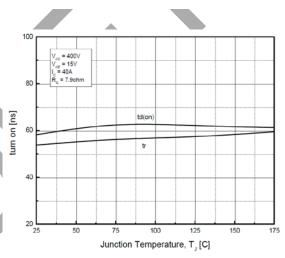


Fig.16 Turn on Characteristics
-Junction Temperature

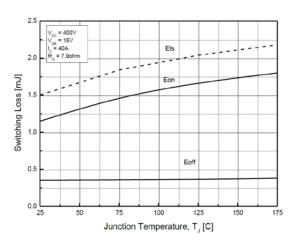


Fig.18 Switching Loss-Junction Temperature



# **Typical Performance Characteristics** (continued)

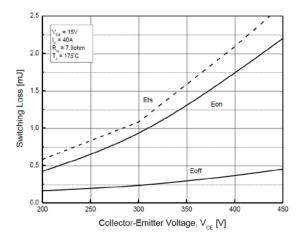


Fig.19 Switching Loss-Collector Emitter Voltage

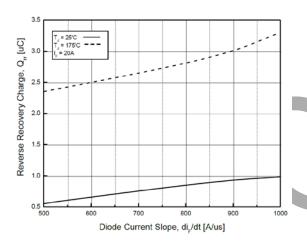


Fig.21 Reverse Recovery Charge -Diode Current Slope

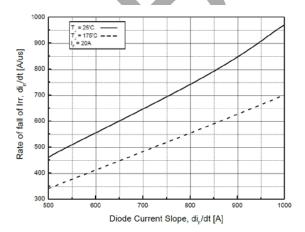


Fig.23 Rate of fall of reverse recovery current
-Diode Current Slope

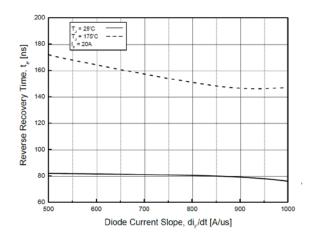


Fig.20 Reverse Recovery Time -Diode current slope

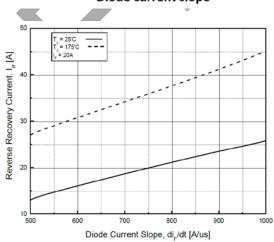


Fig.22 Reverse Recovery Current -Diode current slope

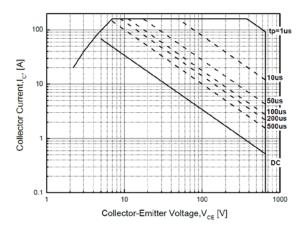


Fig.24 Forward Bias Safe Operating Area



# **Typical Performance Characteristics** (contined)

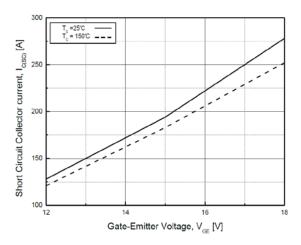


Fig.25 Typical Short Circuit Collector Current

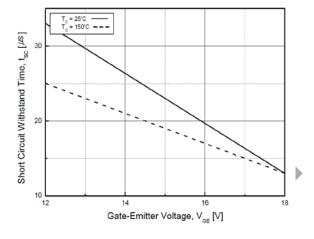


Fig.26 Typical Short Circuit Withstand Time

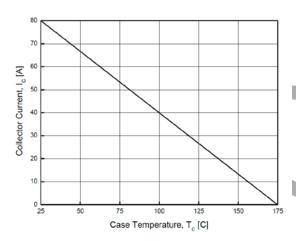


Fig.27 Case Temperature-Collector Current

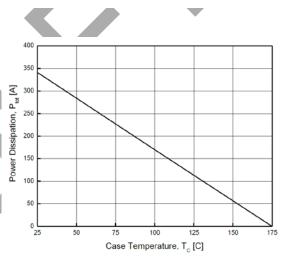


Fig.28 Power Dissipation-Case Temperature

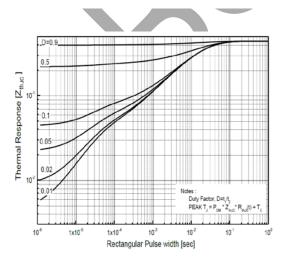


Fig.29 IGBT Transient Thermal Impedance

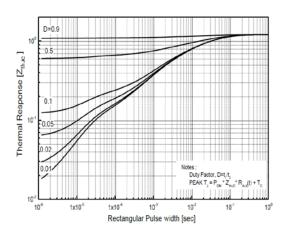


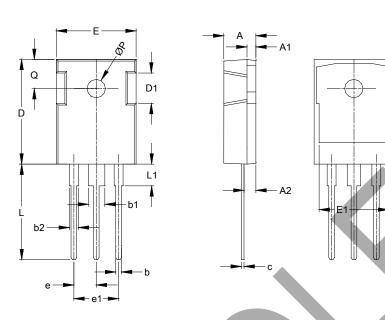
Fig.30 FRD Transient Thermal Impedance



# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### TO247 (Type MC)



TO-247 (Type MC)						
Dim	Min	Тур				
Α	4.700	5.310	_			
A1	1.500	2.490	-			
A2	2.200	2.600	_			
b	0.990	1.400	_			
b1	2.590	3.430				
b2	1.650	2.390				
С	0.380	0.890	_			
D	20.30	21.46	_			
D1	4.320	5.490	_			
D2	13.08	_	_			
E	15.45	16.26	_			
E1	13.06	14.02	_			
е	5.450					
e1	10.90					
L	19.81	20.57	_			
L1	_	4.500	_			
Q	5.380	6.200	_			
øΡ	3.500	3.700	_			
All Dimensions in mm						

Note: For high-voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device terminals and PCB tracking.





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